Title (en)

COMPOSITION FOR CONDUCTIVE PATTERN FORMATION, CONDUCTIVE PATTERN FORMATION METHOD USING SAME, AND RESIN STRUCTURE HAVING CONDUCTIVE PATTERN

Title (de)

ZUSAMMENSETZUNG ZUR BILDUNG EINER LEITFÄHIGEN STRUKTUR, VERFAHREN ZUR BILDUNG EINER LEITFÄHIGEN STRUKTUR DAMIT UND HARZSTRUKTUR MIT LEITFÄHIGER STRUKTUR

Title (fr)

COMPOSITION POUR FORMATION DE MOTIF CONDUCTEUR, PROCÉDÉ DE FORMATION DE MOTIF CONDUCTEUR L'UTILISANT ET STRUCTURE DE RÉSINE AYANT UN MOTIF CONDUCTEUR

Publication

EP 3139388 B1 20191002 (EN)

Application

EP 15835403 A 20150803

Priority

- KR 20140114387 A 20140829
- KR 2015008100 W 20150803

Abstract (en)

[origin: EP3139388A1] Provided are a composition for forming a conductive pattern, which enables formation of a fine conductive pattern onto a variety of polymer resin products or resin layers by a very simplified process, a method of forming the conductive pattern using the same, and a resin structure having the conductive pattern. The composition for forming the conductive pattern includes a polymer resin; and a non-conductive metal compound including a coinage metal element [Group 11 (Group IB)] and a non-metal element, the non-conductive metal compound having a three-dimensional structure formed by vertex sharing of tetrahedrons including the Group 11 metal element, in which a metal core including the Group 11 metal element or an ion thereof is formed from the non-conductive metal compound by electromagnetic irradiation.

IPC 8 full level

H01B 1/22 (2006.01); **H05K 3/10** (2006.01)

CPC (source: EP KR US)

B05D 5/12 (2013.01 - KR); **C08K 3/16** (2013.01 - US); **C09D 5/24** (2013.01 - EP KR US); **C23C 18/1608** (2013.01 - EP US); **C23C 18/1612** (2013.01 - EP US); **C23C 18/204** (2013.01 - EP US); **C23C 18/40** (2013.01 - EP US); **H01B 1/02** (2013.01 - KR); **H01B 1/023** (2013.01 - KR); **H01B 1/026** (2013.01 - KR); **H01B 1/22** (2013.01 - EP KR US); **H01B 5/00** (2013.01 - KR); **H01B 5/14** (2013.01 - KR US); **H01B 13/00** (2013.01 - KR); **H01B 13/0026** (2013.01 - KR US); **H01L 21/00** (2013.01 - KR); **H01L 21/02** (2013.01 - KR); **H01L 21/02348** (2013.01 - KR); **H05K 1/0373** (2013.01 - EP US); **H05K 1/09** (2013.01 - KR US); H05K 3/185 (2013.01 - EP US); H05K 2201/0236 (2013.01 - EP US); H05K 2201/09118 (2013.01 - EP US); H05K 2203/107 (2013.01 - EP US)

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